

U.S. Serial No. 10/052,466
Attorney Docket No. 70434-0024
Amendment under 37 C.F.R. §1.312

IN THE ABSTRACT:

Please amend the abstract of the disclosure on page 19 as follows:

A semiconductor diode has a semiconductor die that includes a substrate, a first semiconductor film, a second semiconductor film, a first metal contact, and a second metal contact. The semiconductor die defines two diagonally opposite first corners and two diagonally opposite second corners. The first semiconductor film has an exposed area that is exposed from the second semiconductor film and that extends between one of the first corners and one of the second corners. The first metal contact is formed on the exposed area and has an extension section and a wire-bonding section that has a width greater than that of the extension section and a length less than that of the extension section. The second metal contact extends between the other one of the first corners and the other one of the second corners and has an extension section and a wire-bonding section that has a width greater than that of the extension section and a length less than that of the extension section.